

MOSTSM: MOS Transistor Sub-um Model for Circuit Simulation
 - Basic I-V Model -

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Abstract

This paper describes a sub-um MOSFET model used as a circuit simulator. The object is to realize a simple model that gives good agreement with experimental result. To achieve this, we have developed (1) a novel formulation for carrier mobility degradation by a gate electric field and (2) a compact channel-length modulation model for MOSFET operation in the saturation region. A maximum I-V model error of 1%, in 0.6um NMOS devices is achieved.

1. MOSTSM Formulation

(a) Weak-inversion model

The following I-V model is used to describe MOSFET sub-threshold conduction.

$$I_{ds} = \beta^* * \left(1 - \exp\left(\frac{-V_d}{V_t}\right) \right) \exp\left(\frac{AV_e}{\beta^*}\right) \quad (2.1)$$

$$\beta^* = \beta_0 \left(\frac{W}{L}\right) \frac{1}{A} \left(\frac{kT}{q}\right)^2 \quad (2.2)$$

where, V_d is drain voltage, V_t ; threshold voltage, A ; sub-threshold slope coefficient, V_e ; effective gate voltage ($=V_g - V_t$), β_0 ; channel conductance of unit gate-area, W and L ; channel width and length, and (kT/q) ; Boltzmann voltage.

(b) Strong-inversion model

We employed simple I-V equations as shown below for the linear operational region:

$$I_{ds} = \frac{W}{L} \beta_{eff} (V_c - \frac{a}{2} V_d) V_d; \quad \text{Linear region} \quad (2.3)$$

$$I_{ds} = \frac{I_{dsat}}{1 - (\delta L/L)}; \quad \text{Saturation region} \quad (2.4)$$

Here, I_{dsat} is saturation drain current, and parameter 'a' exhibits an effective depletion charge effect, which is formulated by.

$$a = 1 + \frac{K_{bo}}{2\sqrt{|V_{b1}| + 2\phi_f}} \left(1 - \frac{1}{1.41 + 0.43(|V_{b1}| + 2\phi_f)} \right) \quad (2.5)$$

where, K_{bo} is substrate-bias constant, V_b ; substrate-bias voltage, and ϕ_f ; Fermi-potential.

In the saturation-region bias condition, the I-V curve is characterized by channel length modulation, ' δL '. we formulate the gate-field effect on the ' β_{eff} ' as;

$$\beta_e = \frac{\beta_0 (\sqrt{\theta_{e1}} + \sqrt{\theta_{e2}})^2 V_c}{(1 + \theta_{e1} V_c) (1 + \theta_{e2} V_c)} \quad (2.6)$$

where, ' $\theta e1$ ' and ' $\theta e2$ ' indicate high and low gate field factors, respectively. It is noted that the β_0 has a unique value independent of device dimensions L and W (channel width).

2. EXPERIMENT

Figure 1 (a) shows an experimental comparison with a conventional MOSFET model which describes the gate field effects on ' β_{eff} ' by ;

$$\beta_{eff} = \frac{\beta_0}{1 + \theta(V_g - V_t)} \quad (3.1)$$

This equation shows monotonic decrease in ' β_{eff} ' as ' V_g ' increases. As shown in the figure, the conventional model demonstrates better agreement with experiment at high gate bias. However, a large discrepancy is observed near the threshold gate bias condition. The MOSTSM model is compared with the experiment as shown in Fig.1 (b) , and excellent agreement with experiment is demonstrated.

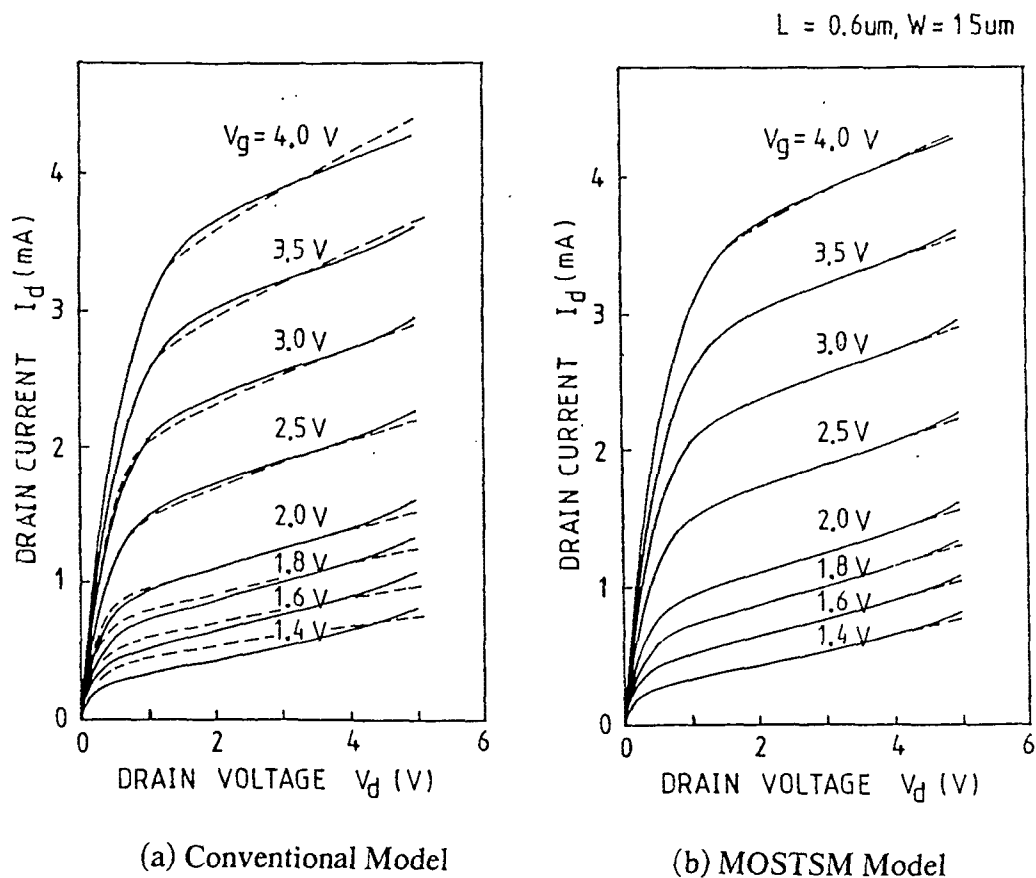


Fig.1 Experimental curve fitting based on the conventional and MOSTSM model at low current bias condition. (solid line: experiment, dashed line: model)